

ON Semiconductor®

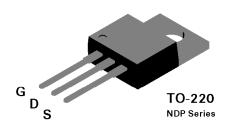
NDP6060L / NDB6060L N-Channel Logic Level Enhancement Mode Field Effect Transistor

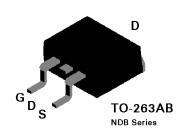
General Description

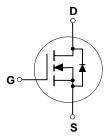
These logic level N-Channel enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, high cell density, DMOS technology. This very high density process has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulses in the avalanche and commutation modes. These devices are particularly suited for low voltage applications such as automotive, DC/DC converters, PWM motor controls, and other battery powered circuits where fast switching, low in-line power loss, and resistance to transients are needed.

Features

- $\blacksquare \quad \text{48A, 60V. } \mathsf{R}_{\scriptscriptstyle \mathsf{DS}(\mathsf{ON})} = 0.025 \Omega \ @ \ \mathsf{V}_{\scriptscriptstyle \mathsf{GS}} = \mathsf{5V}.$
- Low drive requirements allowing operation directly from logic drivers. V_{GS(TH)} < 2.0V.
- Critical DC electrical parameters specified at elevated temperature.
- Rugged internal source-drain diode can eliminate the need for an external Zener diode transient suppressor.
- 175°C maximum junction temperature rating.
- High density cell design for extremely low R_{DS(ON)}.
- TO-220 and TO-263 (D²PAK) package for both through hole and surface mount applications.







Absolute Maximum Ratings

T_C = 25°C unless otherwise noted

Symbol	Parameter	NDP6060L	Units			
V _{DSS}	Drain-Source Voltage	60	V			
V_{DGR}	Drain-Gate Voltage ($R_{GS} \le 1 M\Omega$)	60	V			
V_{GSS}	Gate-Source Voltage - Continuous	±16				
	- Nonrepetitive (t _P < 50 μs)	±25				
l _D	Drain Current - Continuous	48				
	- Pulsed	144				
P_{D}	Total Power Dissipation @ T _C = 25°C	100	W			
	Derate above 25°C	0.67	W/°C			
T_J, T_{STG}	Operating and Storage Temperature	-65 to 175	5	°C		
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	275		°C		

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
DRAIN-S	OURCE AVALANCHE RATINGS (Note 1)						
W _{DSS}	Single Pulse Drain-Source Avalanche Energy	$V_{DD} = 25 \text{ V}, I_{D} = 48 \text{ A}$				200	mJ
I _{AR}	Maximum Drain-Source Avalanche Cui	rrent				48	Α
OFF CHA	ARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$					V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$				250	μA
			T _J = 125°C			1	mA
I _{GSSF}	Gate - Body Leakage, Forward	$V_{GS} = 16 \text{ V}, V_{DS} = 0 \text{ V}$	1 -			100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	V _{GS} = -16 V, V _{DS} = 0 V				-100	nA
	RACTERISTICS (Note 1)			·L	I.	ı	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1		2	V
			T _{.J} = 125°C	0.65		1.5	
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 5 \text{ V}, I_{D} = 24 \text{ A}$, , , , , , , , , , , , , , , , , , ,			0.025	Ω
			T _{.1} = 125°C			0.04	•
		$V_{GS} = 10 \text{ V}, I_{D} = 24 \text{ A}$, , , , , , , , , , , , , , , , , , ,			0.02	•
I _{D(on)}	On-State Drain Current	$V_{GS} = 5 \text{ V}, V_{DS} = 10 \text{ V}$		48			Α
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 24 \text{ A}$		10			S
DYNAMIC	CHARACTERISTICS	1			l.	•	
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, \ V_{GS} = 0 \text{ V},$ f = 1.0 MHz			1630	2000	pF
C _{oss}	Output Capacitance	f = 1.0 MHz			460	800	pF
C _{rss}	Reverse Transfer Capacitance	1			150	400	pF
	NG CHARACTERISTICS (Note 1)			I	I.		
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 30 \text{ V}, I_{D} = 48 \text{ A},$			15	30	nS
t _r	Turn - On Rise Time	$V_{GS} = 5 \text{ V}, R_{GEN} = 15 \Omega,$			320	500	nS
t _{D(off)}	Turn - Off Delay Time	$R_{GS} = 15 \Omega$			49	100	nS
t _f	Turn - Off Fall Time	=			161	300	nS
Q _g	Total Gate Charge	V _{DS} = 48 V,			36	60	nC
Q _{qs}	Gate-Source Charge	$I_D = 48 \text{ A}, V_{GS} = 5 \text{ V}$			8.2		nC
Q _{gd}	Gate-Drain Charge				21		nC

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
DRAIN-SC	OURCE DIODE CHARACTERISTICS	•		•		•	
l _s	Maximum Continuos Drain-Source Diode			48	Α		
I _{SM}	Maximum Pulsed Drain-Source Diode Fo	orward Current				144	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 24 A (Note 1)				1.3	V
			T _J = 125°C			1.2	
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_F = 48 \text{ A},$ $dI_F/dt = 100 \text{ A/}\mu\text{s}$		35	75	140	ns
I _{rr}	Reverse Recovery Current	- αι _ε /αι = 100 Α/μs		2	3.6	8	Α
THERMA	L CHARACTERISTICS						
R _{eJC}	Thermal Resistance, Junction-to-Case					1.5	°C/W
R _{eJA}	Thermal Resistance, Junction-to-Ambier			62.5	°C/W		

Note: 1. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

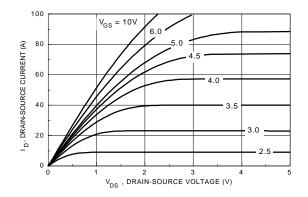


Figure 1. On-Region Characteristics.

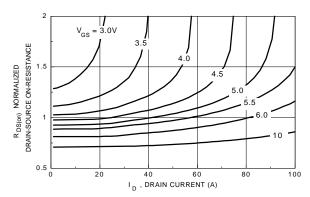


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

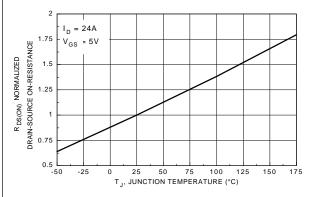


Figure 3. On-Resistance Variation with Temperature.

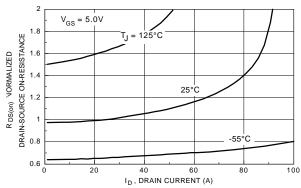


Figure 4. On-Resistance Variation with Drain Current and Temperature.

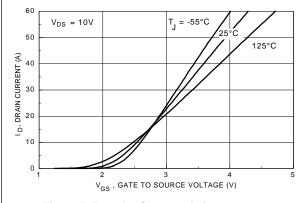


Figure 5. Transfer Characteristics.

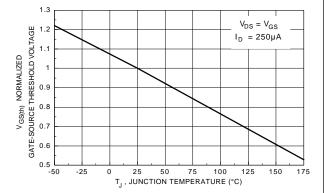


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

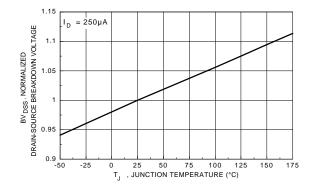


Figure 7. Breakdown Voltage Variation with Temperature.

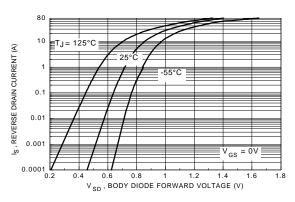


Figure 8. Body Diode Forward Voltage
Variation with Current and Temperature.

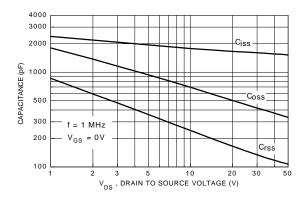


Figure 9. Capacitance Characteristics.

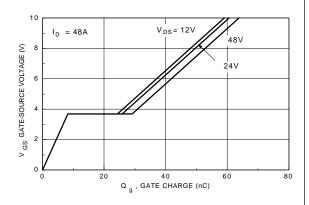


Figure 10. Gate Charge Characteristics.

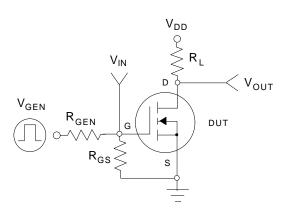


Figure 11. Switching Test Circuit.

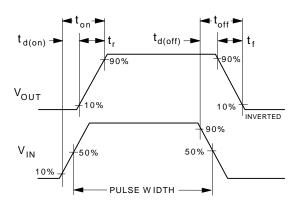
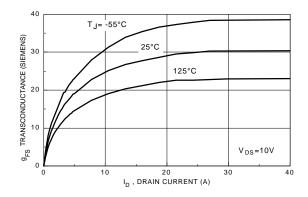


Figure 12. Switching Waveforms.

Typical Electrical Characteristics (continued)



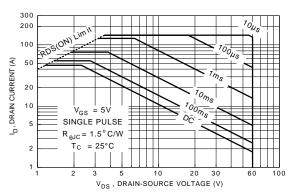


Figure 13. Transconductance Variation with Drain Current. and Temperature

Figure 14. Maximum Safe Operating. Area

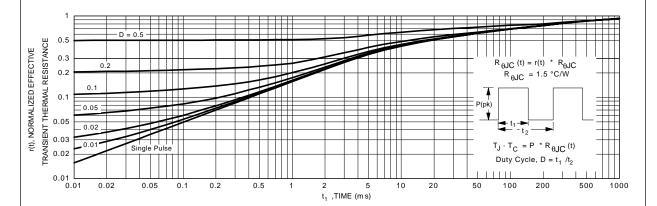
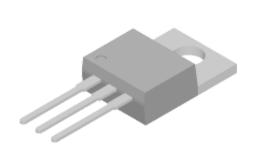


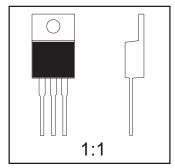
Figure 15. Transient Thermal Response Curve.

TO-220 Tape and Reel Data and Package Dimensions **TO-220 Tube Packing** Configuration: Figure 1.0 Packaging Description: Packaging Description: TO-220 parts are shipped normally in tube. The tube is made of PVC plastic treated with anti-static agent. These tubes in standard option are placed inside a dissipative plastic bag, barcode labeled, and placed inside a box made of recyclable corrugated paper. One box contains two bags maximum (see fig. 1.0). And one or several of these boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped. The other option comes in bulk as described in the Packaging Information table. The units in this option are placed inside a small box laid with antistatic bubble sheet. These smaller boxes are individually labeled and placed inside a larger box (see fig. 3.0). These larger or intermediate boxes then will be placed finally inside a labeled shipping box which still comes in different sizes depending on the number of units shipped. 45 units per Tube per Bag 530mm x 130mm x 83mm Intermediate box 2 bags per Box Conductive Plastic Bag TO-220 Packaging Information: Figure 2.0 1080 units maximum quantity per box TO-220 Packaging Information Packaging Option BULK Packaging type Rail/Tube Qty per Tube/Box 300 FSCINT Label 530x130x83 114x102x51 Box Dimension (mm) Max qty per Box 1,500 1,080 Weight per unit (gm) 1.4378 Note/Comments TO-220 bulk Packing Configuration: Figure 3.0 Anti-static 530mm x 130mm x 83mm **Bubble Sheets FSCINT Label** Intermediate box 1500 units maximum quantity per intermediate box 300 units per EO70 boxes per per Intermediate Box EO70 box 114mm x 102mm x 51mm **FSCINT** Label EO70 Immediate Box TO-220 Tube Configuration: Figure 4.0 Note: All dim ensions are in inches 20.000 +0.031 -0.065

TO-220 Tape and Reel Data and Package Dimensions, continued

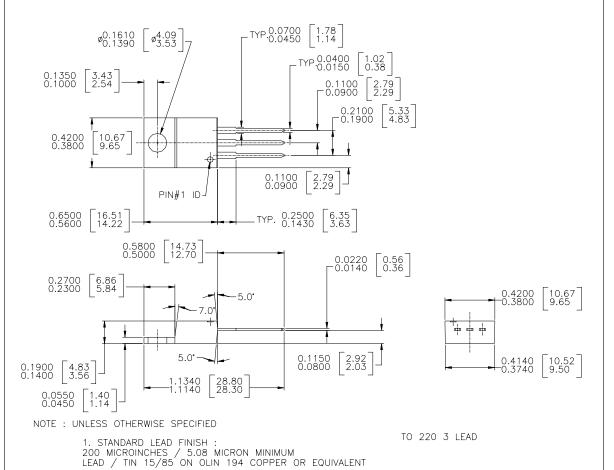
TO-220 (FS PKG Code 37)



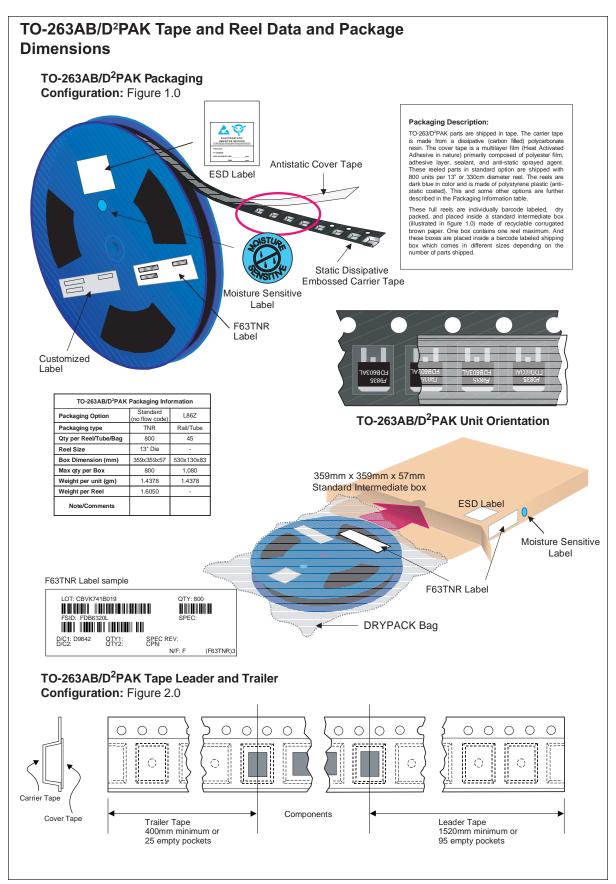


Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 1.4378

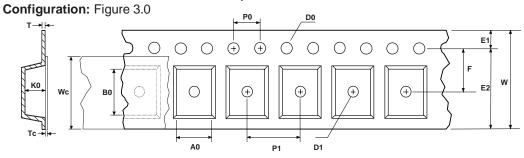


2. DIMENSION BASED ON JEDEC STANDARD TO-220 VARIATION AB, ISSUE J, DATED 3/24/87



TO-263AB/D²PAK Tape and Reel Data and Package Dimensions, continued

TO-263AB/D²PAK Embossed Carrier Tape



User Direction of Feed

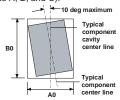
Dimensions are in millimeter														
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	Т	Wc	Тс
TO263AB/ D²PAK (24mm)	10.60 +/-0.10	15.80 +/-0.10	24.0 +/-0.3	1.55 +/-0.05	1.60 +/-0.10	1.75 +/-0.10	22.25 min	11.50 +/-0.10	16.0 +/-0.1	4.0 +/-0.1	4.90 +/-0.10	0.450 +/-0.150	21.0 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)

Component Rotation



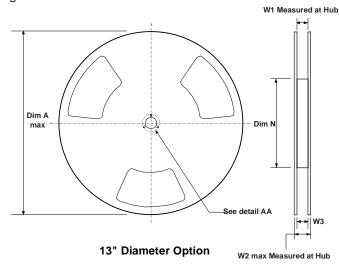
Sketch B (Top View)
Component Rotation

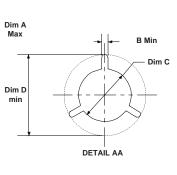


Sketch C (Top View)

Component lateral movement

TO-263AB/D²PAK Reel Configuration: Figure 4.0

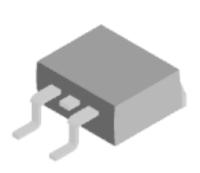


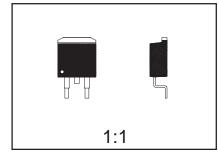


Dimensions are in inches and millimeters											
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)		
24mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.961 +0.078/-0.000 24.4 +2/0	1.197 30.4	0.941 - 0.1.079 23.9 - 27.4		

TO-263AB/D²PAK Tape and Reel Data and Package Dimensions, continued

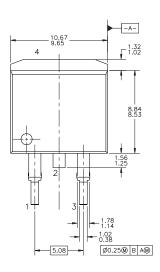
TO-263AB/D²PAK (FS PKG Code 45)

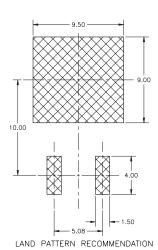


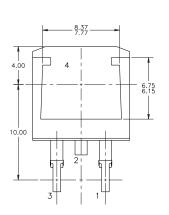


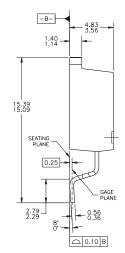
Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 1.4378









- NOTES: UNLESS OTHERWISE SPECIFIED

 A) ALL DIMENSIONS ARE IN MILLIMETERS.
 B) STANDARD LEAD FINISH:
 200 MICROINCHES / 5.08 MICROMETERS MIN.
 LEAD/TIN 15/85 ON OLIN 194 COPPER OR
 EQUIVALENT.
 C) MAXIMUM YERTICAL BURR ON HEATSINK NOT
 TO EXCEED 0.003 INCH / 0.05mm.
 D) NO PACKAGE CHIPS, CRACKS OR SURFACE
 IDENTIFICATION ALLOWED AFTER FORMING.
 E) REFERENCE JEDEC, TO—265, ISSUE C,
 VARIATION AB, DATED 2/92.

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